



<b>Session Title:</b>	<b>[WeE3] Plasma Source Technology</b>
<b>Session Date:</b>	<b>November 13 (Wed.), 2024</b>
<b>Session Time:</b>	<b>16:05-17:35</b>
<b>Session Room:</b>	<b>Room E (Sicily Room, 1F, Paradise Hotel Busan)</b>
<b>Session Chair:</b>	<b>Prof. Ho-Jun Lee (Pusan Nat'l Univ., Korea)</b>

**[WeE3-1] [Invited]**

**16:05-16:35**

**Advances in Pulsed RF Power Delivery for Plasma Processes**

Steven Shannon (North Carolina State Univ., USA)

**[WeE3-2]**

**16:35-16:55**

**Charge-Free Plasma Processing Using Ultra-Low Electron Temperature Plasma for Atomic Scale Semiconductor Devices**

Min-Seok Kim, Na Yeon Kim, Junyoung Park, and Chin-Wook Chung (Hanyang Univ., Korea)

**[WeE3-3]**

**16:55-17:15**

**Microwave Heating Techniques in Wafer Processing: Utilizing Toroidal Slot Antennas and Resonant Cavity Modes**

Sung-Hyeon Jung, Sang-Woo Kim (Pusan Nat'l Univ., Korea), Ju-Hong Cha (Gyeongsang Nat'l Univ., Korea), and Ho-Jun Lee (Pusan Nat'l Univ., Korea)

**[WeE3-4]**

**17:15-17:35**

**Enhancement of Plasma Characteristics by Using 2.45[GHz] Microwave Source in Inductively Coupled Plasma**

Dong-Jin Kang, Sang-Woo Kim (Pusan Nat'l Univ., Korea), Ju-Hong Cha (Gyeongsang Nat'l Univ., Korea), and Ho-Jun Lee (Pusan Nat'l Univ., Korea)